

P-Channel 20-V (D-S) MOSFET

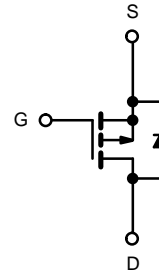
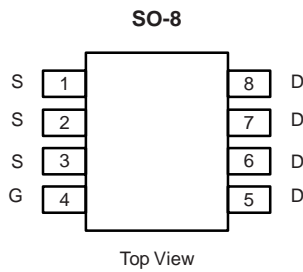
PRODUCT SUMMARY		
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A)
- 20	0.042 at V _{GS} = - 4.5 V	- 6.6
	0.054 at V _{GS} = - 2.5 V	- 4.4

FEATURES

- DT-Trench Power MOSFET
- Compliant to RoHS Directive 2002/95/EC



RoHS
COMPLIANT



P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted				
Parameter	Symbol	10 s	Steady State	Unit
Drain-Source Voltage	V _{DS}	- 20		V
Gate-Source Voltage	V _{GS}	± 12		
Continuous Drain Current (T _J = 150 °C) ^a	I _D	T _A = 25 °C	- 6.6	- 4.1
		T _A = 70 °C	- 4.6	- 3.2
Pulsed Drain Current	I _{DM}	- 30		A
Continuous Source Current (Diode Conduction) ^a	I _S	- 2.3	- 1.1	
Maximum Power Dissipation ^a	P _D	T _A = 25 °C	2.5	1.3
		T _A = 70 °C	1.6	0.8
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 150		°C

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^a	R _{thJA}	t ≤ 10 s	40	50	°C/W
		Steady State	70	95	
Maximum Junction-to-Foot (Drain)	R _{thJF}	24	30		

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

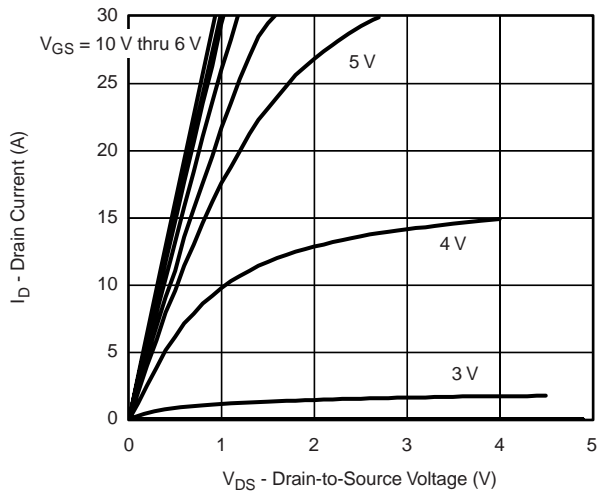
SPECIFICATIONS $T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted						
Parameter	Symbol	Test Conditions	Min.	Typ. ^a	Max.	Unit
Static						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\text{ }\mu\text{A}$	- 1.0		- 3.0	V
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0\text{ V}, V_{GS} = \pm 12\text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -20\text{ V}, V_{GS} = 0\text{ V}$			- 1	μA
		$V_{DS} = -20\text{ V}, V_{GS} = 0\text{ V}, T_J = 70\text{ }^\circ\text{C}$			- 5	
On-State Drain Current ^b	$I_{D(on)}$	$V_{DS} \leq -10\text{ V}, V_{GS} = -4.5\text{ V}$	- 20			A
		$V_{DS} \leq -5\text{ V}, V_{GS} = -4.5\text{ V}$	- 5			
Drain-Source On-State Resistance ^b	$R_{DS(on)}$	$V_{GS} = -4.5\text{ V}, I_D = -5\text{ A}$		0.042	0.047	Ω
		$V_{GS} = -2.5\text{ V}, I_D = -4.4\text{ A}$		0.054	0.060	
Forward Transconductance ^b	g_{fs}	$V_{DS} = -15\text{ V}, I_D = -5.8\text{ A}$		13		S
Diode Forward Voltage ^b	V_{SD}	$I_S = -2.3\text{ A}, V_{GS} = 0\text{ V}$		- 0.8	- 1.1	V
Dynamic^a						
Total Gate Charge	Q_g	$V_{DS} = -15\text{ V}, V_{GS} = -4.5\text{ V}, I_D = -3.5\text{ A}$		16	24	nC
Gate-Source Charge	Q_{gs}			2.3		
Gate-Drain Charge	Q_{gd}			4.5		
Gate Resistance	R_g			8.8		Ω
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = -15\text{ V}, R_L = 15\text{ }\Omega$ $I_D \cong -1\text{ A}, V_{GEN} = -4.5\text{ V}, R_g = 6\text{ }\Omega$		14	25	ns
Rise Time	t_r			14	25	
Turn-Off Delay Time	$t_{d(off)}$			42	70	
Fall Time	t_f			30	50	
Source-Drain Reverse Recovery Time	t_{rr}	$I_F = -1.2\text{ A}, dI/dt = 100\text{ A}/\mu\text{s}$		30	60	

Notes:

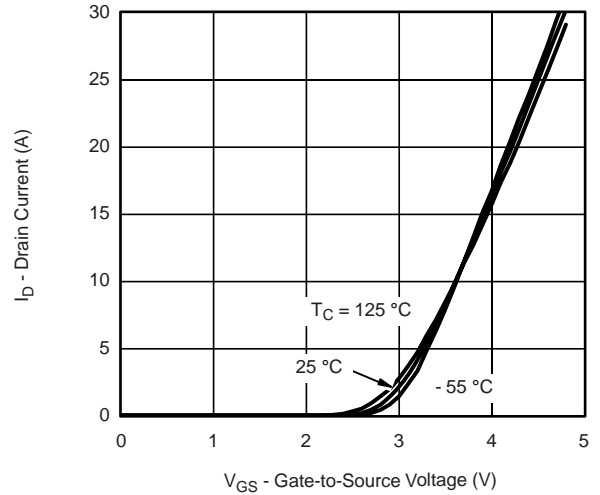
- a. Guaranteed by design, not subject to production testing.
 b. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

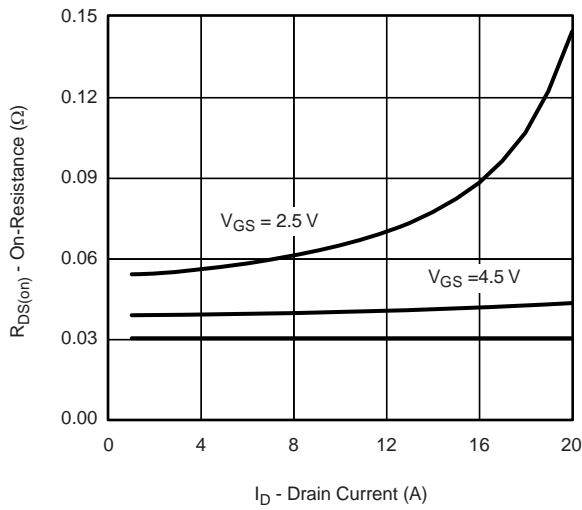
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



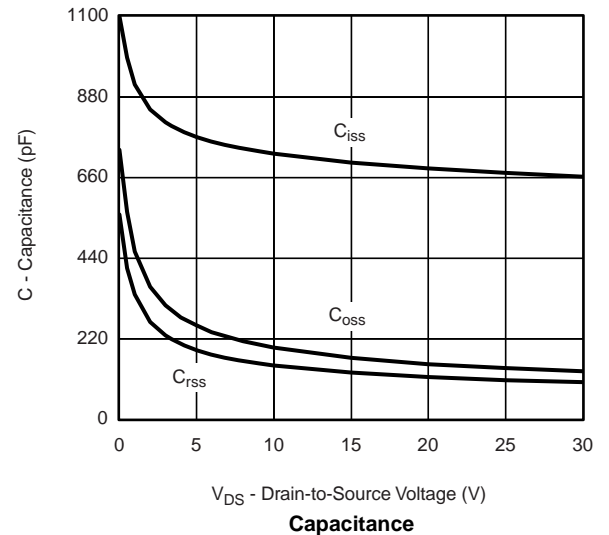
Output Characteristics



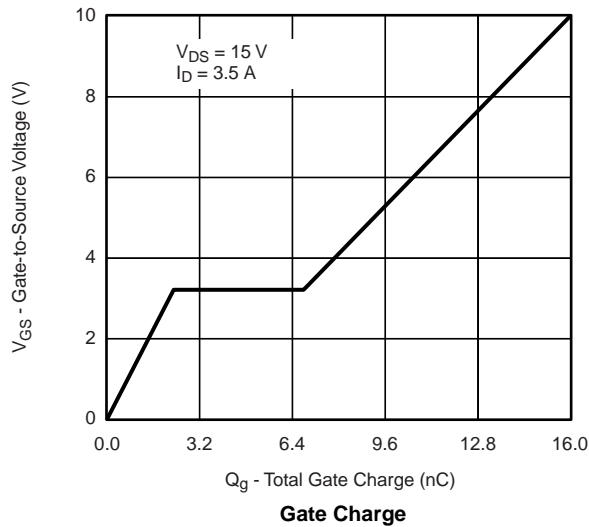
Transfer Characteristics



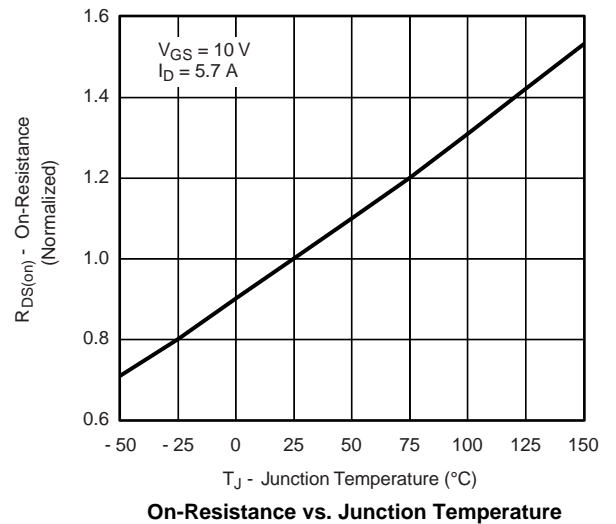
On-Resistance vs. Drain Current



Capacitance

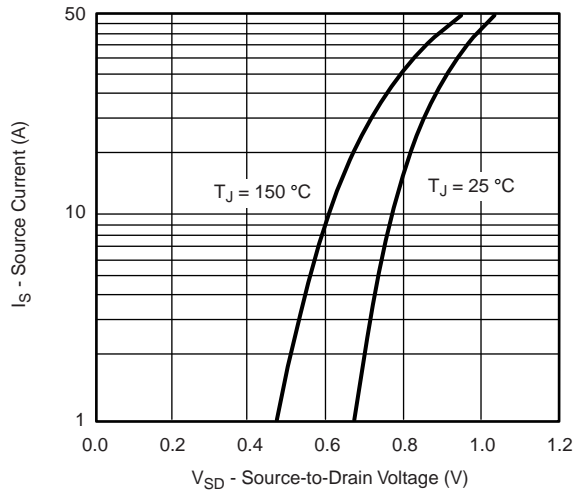


Gate Charge

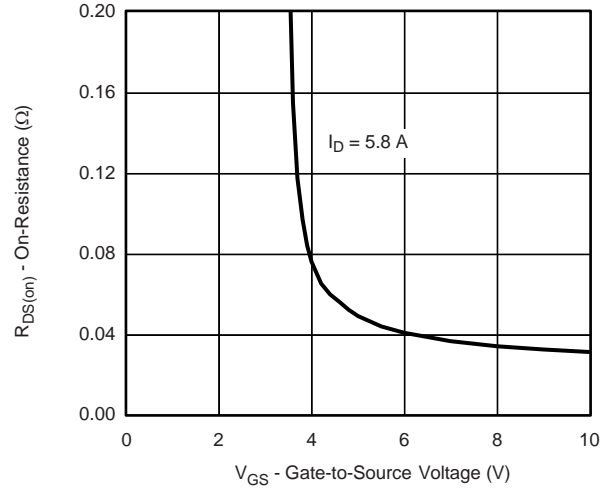


On-Resistance vs. Junction Temperature

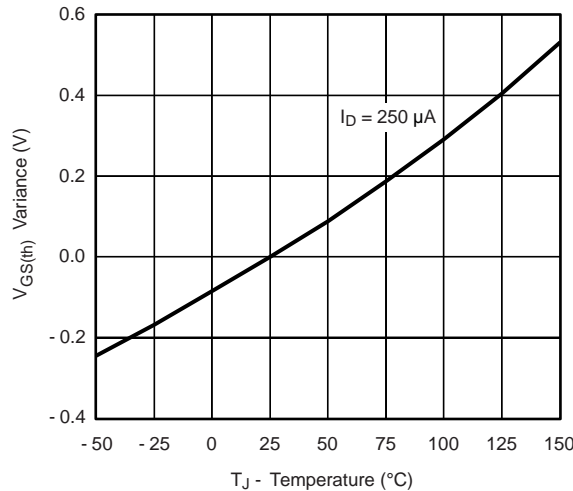
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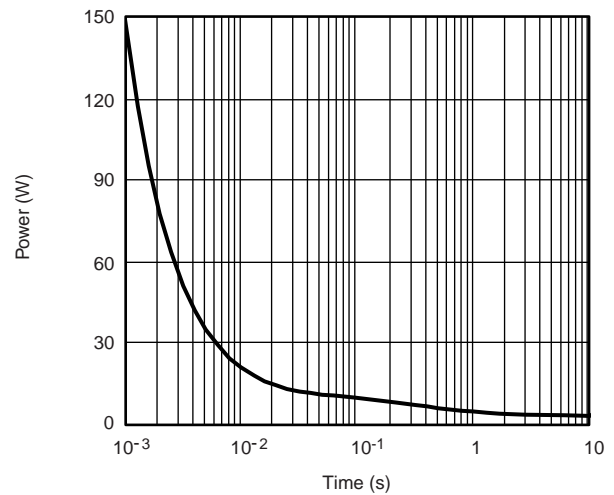
Source-Drain Diode Forward Voltage



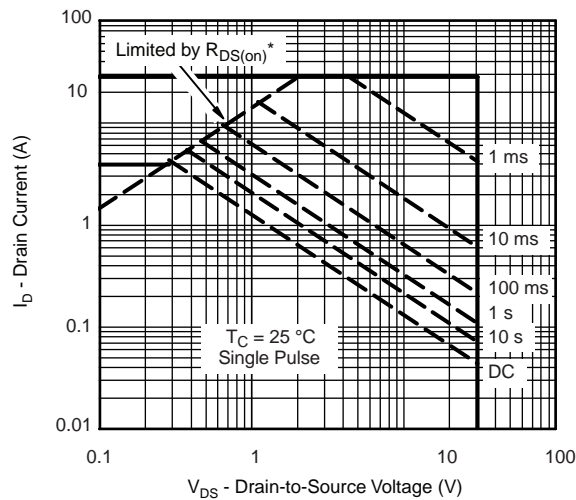
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



Single Pulse Power, Junction-to-Ambient



* $V_{DS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Foot

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

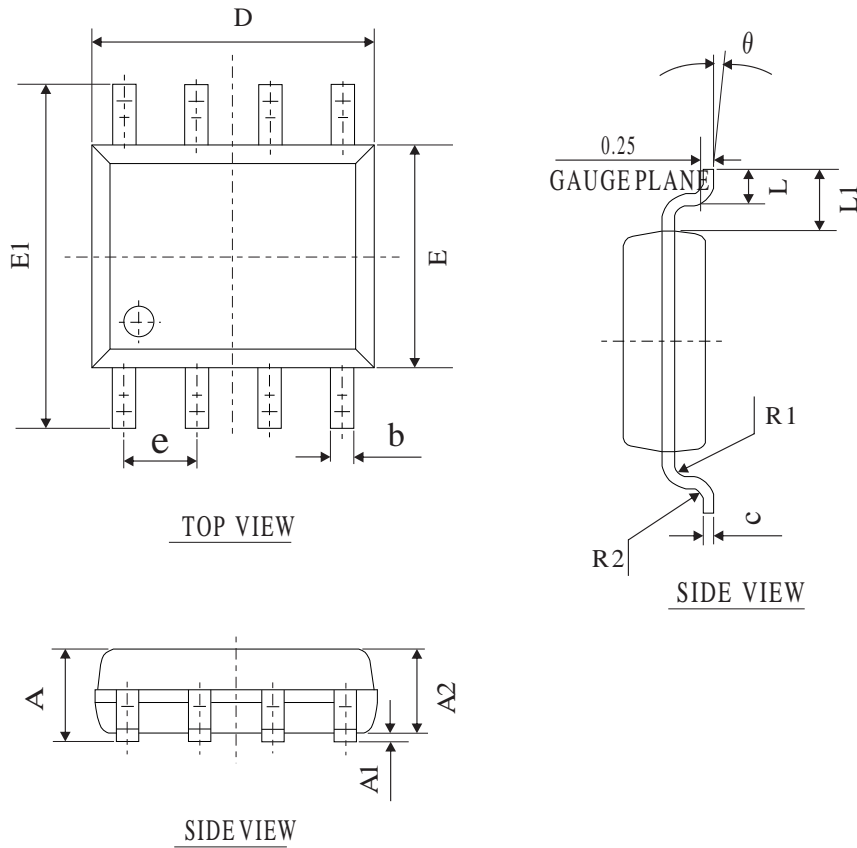


Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

SOP-8 PACKAGE OUTLINE



COMMON DIMENSIONS
(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	TYP	MAX
A	1.30	1.60	1.85
A1	0.03	0.15	0.28
A2	1.20	1.45	1.70
b	0.26	0.40	0.54
C	0.132	0.203	0.273
D	4.50	4.90	5.30
E	3.50	3.00	4.30
E1	5.50	6.00	6.50
L	0.30	0.70	1.10
θ	2°	4°	6°
L1	1.04REF		
e	1.27BSC		
R1	0.07TYP		
R2	0.07TYP		

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